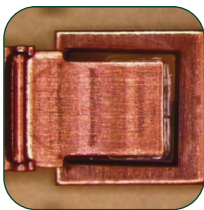
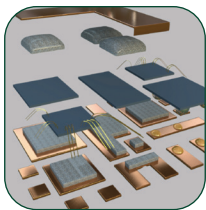


# NC-SMQ75 Power Semiconductor Die-Attach Solder Paste

Best in  
class!



- Ultra-low post-reflow residue <0.5% w/w of solder paste
- “Power-Safe” residue compatible with overmolding compounds without delamination
- Consistent dispensing deposit size without clogging
- Wide range of alloy compatibility
- Reflow up to 400°C in low oxygen or forming gas atmosphere (<100ppmO<sub>2</sub>)
- Low-voiding
- Good wetting with common metal finishes



Contact our engineers: [askus@indium.com](mailto:askus@indium.com)  
Learn more: [www.indium.com](http://www.indium.com)

*All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.*

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Form No. 99579 R1



INDIUM  
CORPORATION®

The logo for Indium Corporation, featuring a stylized 'i' and 'n' symbol above the company name 'INDIUM CORPORATION' in a bold, sans-serif font. The logo is set against a dark green circular background.

# Standard Die-Attach Solder Paste Alloys

Commonly used alloy		Elemental % w/w						°C	
Pb-free	Comments	Sn	Ag	Sb	Pb	Au	In	Solidus	Liquidus
	Low Tj IGBT usage	96.5	3.5						221
High-reliability	65	25	10					233	340
Most common Sb-based alloy	90		10					243	257
High tensile strength; high cost	20					80		280	Eutectic
Pb-containing	Good tilt control		2.5		92.5		5	300	310
	Automotive usage	5			95			308	312
		10			90			275	302
		5	2.5		92.5			287	296
		2	2.5		95.5			299	304

## Major Users

- All major power semiconductor IDMs and OSATs
- Mobile, consumer, automotive, etc.



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